

Yu-An Shen

List of Publications by Year in descending order

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38
papers

510
citations

623188

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676716

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all docs

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docs citations

40
times ranked

202
citing authors

#	ARTICLE	IF	CITATIONS
1	Effect of Sn grain orientation on formation of Cu ₆ Sn ₅ intermetallic compounds during electromigration. <i>Scripta Materialia</i> , 2017, 128, 6-9.	2.6	69
2	Sn-3.0Ag-0.5Cu/Sn-58Bi composite solder joint assembled using a low-temperature reflow process for PoP technology. <i>Materials and Design</i> , 2019, 183, 108144.	3.3	47
3	The newly developed Sn-Bi-Zn alloy with a low melting point, improved ductility, and high ultimate tensile strength. <i>Materialia</i> , 2019, 6, 100300.	1.3	35
4	Thermomigration induced microstructure and property changes in Sn-58Bi solders. <i>Materials and Design</i> , 2019, 166, 107619.	3.3	35
5	Effect of Sn grain orientation on growth of Cu-Sn intermetallic compounds during thermomigration in Cu-Sn _{2.3} Ag-Ni microbumps. <i>Materials Letters</i> , 2019, 236, 190-193.	1.3	26
6	Investigation of FeCoNiCu properties: Thermal stability, corrosion behavior, wettability with Sn-3.0Ag-0.5Cu and interlayer formation of multi-element intermetallic compound. <i>Applied Surface Science</i> , 2021, 546, 148931.	3.1	23
7	Effect of Substrates on Fracture Mechanism and Process Optimization of Oxidation-Reduction Bonding with Copper Microparticles. <i>Journal of Electronic Materials</i> , 2019, 48, 2263-2271.	1.0	22
8	Extremely thin interlayer of multi-element intermetallic compound between Sn-based solders and FeCoNiMn high-entropy alloy. <i>Applied Surface Science</i> , 2021, 558, 149945.	3.1	21
9	Graphene as a diffusion barrier at the interface of Liquid-State low-melting Sn-58Bi alloy and copper foil. <i>Applied Surface Science</i> , 2022, 578, 152108.	3.1	18
10	In-situ observation of fluxless soldering of Sn-3.0Ag-0.5Cu/Cu under a formic acid atmosphere. <i>Materials Chemistry and Physics</i> , 2020, 239, 122309.	2.0	17
11	Improved mechanical properties induced by In and In & Zn double additions to eutectic Sn58Bi alloy. <i>Journal of Materials Science: Materials in Electronics</i> , 2019, 30, 7423-7434.	1.1	16
12	Novel polarity effect on intermetallic compound thickness changes during electromigration in Cu/Sn-3.0Ag-0.5Cu/Cu solder joints. <i>Journal of Applied Physics</i> , 2019, 126, .	1.1	15
13	Interfacial transformation of preoxidized Cu microparticles in a formic-acid atmosphere for pressureless Cu-Cu bonding. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 14635-14644.	1.1	15
14	Electrodeposition of Twinned Cu with Strong Texture Effect on Voiding Propensity in Electroplated Cu Solder Joints. <i>Journal of the Electrochemical Society</i> , 2020, 167, 162516.	1.3	15
15	Wettability, interfacial reactions, and impact strength of Sn-3.0Ag-0.5Cu solder/ENIG substrate used for fluxless soldering under formic acid atmosphere. <i>Journal of Materials Science</i> , 2020, 55, 3107-3117.	1.7	14
16	Preferred orientation of Bi and effect of Sn-Bi microstructure on mechanical and thermomechanical properties in eutectic Sn-Bi alloy. <i>Materialia</i> , 2019, 6, 100309.	1.3	13
17	Suppressed Growth of (Fe, Cr, Co, Ni, Cu)Sn ₂ Intermetallic Compound at Interface between Sn-3.0Ag-0.5Cu Solder and FeCoNiCrCu _{0.5} Substrate during Solid-state Aging. <i>Scientific Reports</i> , 2019, 9, 10210.	1.6	12
18	Microstructure and mechanical properties of the In ₄₈ Sn _x Ag low-temperature alloy. <i>Journal of Materials Science</i> , 2020, 55, 10824-10832.	1.7	11

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19	Effect of Cu addition on the microstructure and mechanical properties of In-Sn-based low-temperature alloy. <i>Materials Science & Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , 2021, 804, 140785.	2.6	11
20	Effect of FeCoNiCrCu0.5 High-entropy-alloy Substrate on Sn Grain Size in Sn-3.0Ag-0.5Cu Solder. <i>Scientific Reports</i> , 2019, 9, 3658.	1.6	10
21	Effect of Cu on the interfacial reaction between Sn-based solders and FeCoNiCu alloys. <i>Intermetallics</i> , 2022, 144, 107530.	1.8	9
22	Anisotropic Grain Growth in (111) Nanotwinned Cu Films by DC Electrodeposition. <i>Materials</i> , 2020, 13, 134.	1.3	8
23	Fabrication of NiO/ZrO ₂ nanocomposites using ball milling-pyrolysis method. <i>Vacuum</i> , 2021, 191, 110370.	1.6	8
24	Microstructure Evolution and Shear Strength of Tin-Indium-xCu/Cu Joints. <i>Metals</i> , 2022, 12, 33.	1.0	7
25	Electromigration behavior of silver thin film fabricated by electron-beam physical vapor deposition. <i>Journal of Materials Science</i> , 2021, 56, 9769-9779.	1.7	6
26	Nanotwin orientation on history-dependent stress decay in Cu nanopillar under constant strain. <i>Nanotechnology</i> , 2022, 33, 155708.	1.3	6
27	A Cu-Cu Bonding Method Using Preoxidized Cu Microparticles under Formic Acid Atmosphere. , 2019, , .		5
28	Effects of impurities on void formation at the interface between Sn-3.0Ag-0.5Cu and Cu electroplated films. <i>Journal of Materials Science: Materials in Electronics</i> , 2021, 32, 11944-11951.	1.1	4
29	Microstructure and Property Changes in Cu/Sn-58Bi/Cu Solder Joints During Thermomigration. , 2019, , .		3
30	Effects of In and Zn Double Addition on Eutectic Sn-58Bi Alloy. , 2019, , .		2
31	Mechanical and microstructural enhancements of Ag microparticle-sintered joint by ultrasonic vibration. <i>Journal of Materials Science: Materials in Electronics</i> , 2020, 31, 21711-21722.	1.1	2
32	Observation of void formation patterns in SnAg films undergoing electromigration and simulation using random walk methods. <i>Scientific Reports</i> , 2021, 11, 8668.	1.6	2
33	Contact Angle Analysis and Intermetallic Compounds Formation Between Solders and Substrates under Formic acid Atmosphere. <i>Journal of Advanced Joining Processes</i> , 2022, , 100118.	1.5	1
34	A Study on Strengthening Mechanisms in Sn-0.7Cu via Microstructural Observation, Elemental Distribution, and Grain-Size Analysis. , 2022, , .		1
35	Study of grain size and orientation of 30 Åµm solder microbumps bonded by thermal compression. , 2015, , .		0
36	Effect of Sn grain orientation on the formation of Cu ₆ S ₅ intermetallic compounds during electromigration. , 2016, , .		0

#	ARTICLE	IF	CITATIONS
37	The study of Sn-45Bi-2.6Zn alloy before and after thermal aging. , 2019, , .		0
38	The voids growth path on Sn-Ag thin film under high current density. , 2021, , .		0